

Title (en)
PLANAR SENSOR AND ITS MANUFACTURING METHOD

Title (de)
PLANARER SENSOR UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)
CAPTEUR PLANAIRE ET SON PROCÉDÉ DE FABRICATION

Publication
EP 2766885 A1 20140820 (EN)

Application
EP 12830705 A 20120904

Priority
• FI 20115869 A 20110905
• FI 2012050854 W 20120904

Abstract (en)
[origin: WO2013034802A1] A planar sensor having a conductor pattern for electric field sensing and its manufacturing method, the planar sensor comprising arrays of planar electrically conductive sensor areas (2) arranged to follow each other in a successive manner along the longitudinal direction, and conductors connecting electrically conductive sensor area to at least one connector, wherein the sensor further comprises a first elastic flooring layer (3) and at least one of the following: a second elastic flooring layer (4) or a flexible circuit board, and the electrically conductive sensor areas (2) and the conductors are attached between the first elastic flooring layer (3) and the second elastic flooring layer (4) or between the first elastic flooring layer (3) and the flexible circuit board to form a unitary floor sensor structure.

IPC 8 full level
G08B 13/10 (2006.01); **G01D 5/24** (2006.01); **H03K 17/96** (2006.01); **G01R 29/14** (2006.01); **G01V 3/02** (2006.01); **H05K 3/00** (2006.01); **H05K 3/28** (2006.01)

CPC (source: EP US)
B32B 37/02 (2013.01 - US); **B32B 37/18** (2013.01 - US); **G01B 7/003** (2013.01 - US); **G01B 7/14** (2013.01 - US); **G01D 5/2405** (2013.01 - EP US); **G01N 27/041** (2013.01 - US); **H03K 17/9622** (2013.01 - EP US); **B32B 2307/51** (2013.01 - US); **B32B 2457/08** (2013.01 - US); **B32B 2471/00** (2013.01 - US); **G01R 29/14** (2013.01 - EP US); **G01V 3/02** (2013.01 - EP US); **G08B 13/10** (2013.01 - EP US); **H03K 2017/9602** (2013.01 - EP US); **H03K 2217/96015** (2013.01 - EP US); **H03K 2217/960755** (2013.01 - EP US); **H05K 1/118** (2013.01 - EP US); **H05K 3/281** (2013.01 - EP US); **H05K 2203/1545** (2013.01 - EP US); **Y10T 156/1089** (2015.01 - EP US)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
WO 2013034802 A1 20130314; AU 2012306230 A1 20140313; AU 2012306230 B2 20160107; CA 2844578 A1 20130314; CN 103843041 A 20140604; CN 103843041 B 20160831; DK 2766885 T3 20190114; EP 2766885 A1 20140820; EP 2766885 A4 20150408; EP 2766885 B1 20181010; ES 2702559 T3 20190301; FI 20115869 A0 20110905; JP 2014531579 A 20141127; KR 20140057378 A 20140512; RU 2014113095 A 20151020; TR 201818937 T4 20190121; US 2015077142 A1 20150319; US 9506884 B2 20161129

DOCDB simple family (application)
FI 2012050854 W 20120904; AU 2012306230 A 20120904; CA 2844578 A 20120904; CN 201280043245 A 20120904; DK 12830705 T 20120904; EP 12830705 A 20120904; ES 12830705 T 20120904; FI 20115869 A 20110905; JP 2014529036 A 20120904; KR 20147008705 A 20120904; RU 2014113095 A 20120904; TR 201818937 T 20120904; US 201214239453 A 20120904